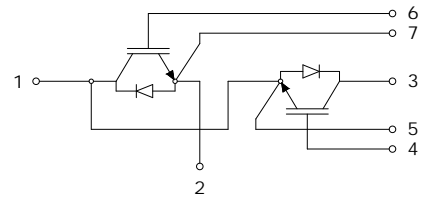


PRELIMINARY DATASHEET
1200V 228A, Highly Rugged SPT+ IGBT in iQpak® 2 Module Package
APPLICATION

- Motor drives
- UPS
- High power inverters
- Induction heating

FEATURES

- High speed switching
- Low turn-off losses
- Low conduction loss: $V_{CE(sat)typ} = 1.87V$
- Fast & soft anti-parallel diode
- Pb free finished; **RoHS compliant**


MAXIMUM RATINGS (per Leg)

Parameter	Symbol	Value	Units
Collector-emitter voltage	V_{CES}	1200	V
DC collector current $T_C=80^\circ C$	I_C	228	A
Peak collector current	I_{CM}	456	
Diode forward current $T_C=80^\circ C$	I_F	200	
Peak forward current	I_{FM}	400	
Gate-emitter voltage	V_{GE}	± 20	V
IGBT short circuit SOA $V_{CC} = 1200V, V_{GE} = 15V, V_{CEM} < 1200V, T_{VJ} \leq 125^\circ C$	t_{SC}	10	μs
Operating junction and storage temperature	T_j, T_{stg}	-40... +150	$^\circ C$

Thermal and Isolation Characteristics

Parameter	Symbol	Max. Value	Units
Characteristics			
IGBT thermal resistance, junction to case	R_{thJC}	0.11	K/W
Diode thermal resistance, junction to case	R_{thJCD}	0.16	
Isolation voltage, RMS (measured between terminals and mounting base, 50-60 Hz, for 1-3 seconds)	V_{iso}	3000	V

Electrical characteristics (per Leg), at $T_j = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Conditions	Value			Unit
			Min.	Typ.	Max.	
Static Characteristics						
Collector-emitter breakdown voltage	$V_{(BR)CES}$	$V_{GE} = 0V, I_C = 4mA$	1200	-	-	V
Collector-emitter saturation voltage	$V_{CE(sat)}$	$V_{GE} = 15V, I_C = 228A$ $V_{GE} = 15V, I_C = 200A$	1.7 -	1.87 -	2.0 1.74	
Diode forward voltage	V_F	$V_{GE} = 0V, I_F = 200A$	-	1.8	2.2	
Gate-emitter threshold voltage	$V_{GE(th)}$	$I_C = 8 mA, V_{CE} = V_{GE}$	5.0	6.3	7	
Zero gate voltage collector current	I_{CES}	$V_{CE} = 1200V, V_{GE} = 0$ $T = 25^\circ\text{C}$	-	-	400	μA
Gate-emitter leakage current	I_{GES}	$V_{CE} = 0V, V_{GE} = \pm 20V,$	-200	-	200	nA
Internal gate resistance	R_{Gint}		-	2.5	-	Ω

Electrical Characteristics (per Leg), at $T_j = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Conditions	Value			Unit
			Min.	Typ.	Max.	
Dynamic Characteristics						
Gate charge	Q_{ge}	$I_C = 228A, V_{CE} = 600V,$ $V_{GE} = \pm 15V$	-	2444	-	nC
Input capacitance	C_{iss}	$V_{CE} = 25V,$	-	17.2	-	nF
Output capacitance	C_{oss}	$V_{GE} = 0V,$	-	1.2	-	
Reverse transfer capacitance	C_{rfs}	$f = 1\text{MHz}$	-	0.8	-	
Short circuit current	I_{SC}	$T_C = 125^\circ\text{C},$ $V_{CC} = 900V, V_{GE} = 15V,$ $t_{psc} \leq 10\mu\text{s},$ $V_{CEM} \leq 1200V$	-	1080	-	A

Switching Characteristics (per Leg), at $T_j = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Conditions	Value			Unit
			Min.	Typ.	Max.	
IGBT Characteristics						
Turn-on delay time	$t_{d(on)}$	$V_{CC} = 600V, I_C = 228A,$ $V_{GE} = -15V \text{ to } 18V,$ $R_G = 3.4\Omega,$ Inductive load.	-	355	-	ns
Rise time	t_r		-	53	-	
Turn-off delay time	$t_{d(off)}$		-	469	-	
Fall time	t_f		-	55	-	
Turn-ON energy	E_{on}		-	33	-	mJ
Turn-OFF energy	E_{off}		-	9	-	

Anti-Parallel Diode Characteristics (per Leg), at $T_j = 25^\circ\text{C}$, unless otherwise specified

Diode reverse recovery time	t_{rr}	$V_R = 600V, I_F = 200A$ $di_F/dt = 650A/\mu\text{s}$ Inductive load	-	618	-	ns
Diode reverse recovery charge	Q_{rr}		-	23	-	μC
Diode peak reverse recovery current	I_{rrm}		-	57	-	A

Figure 1: Typical IGBT turn-on switching times vs R_G , $T_j = 25^\circ\text{C}$

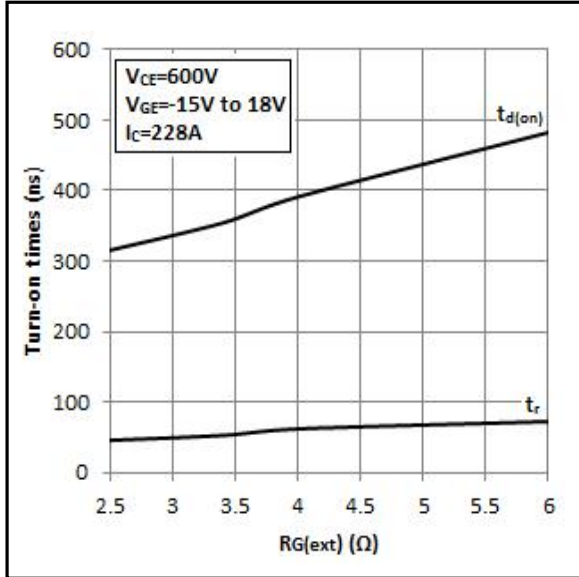


Figure 2: Typical IGBT turn-off switching times vs R_G , $T_j = 25^\circ\text{C}$

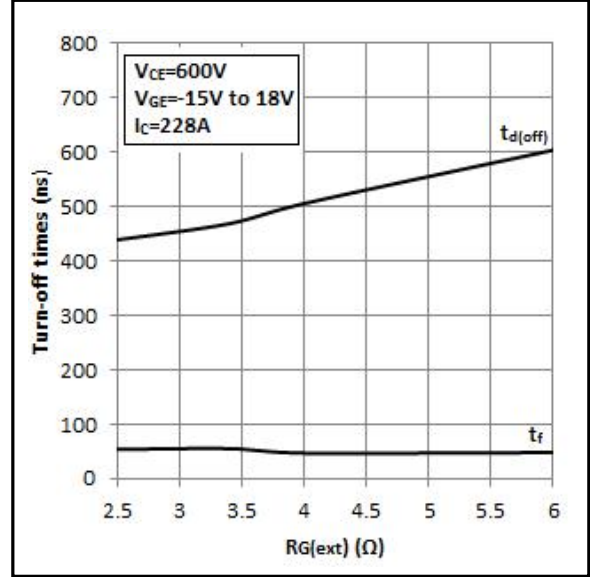


Figure 3: Typical IGBT turn-on switching times vs I_C , $T_j = 25^\circ\text{C}$

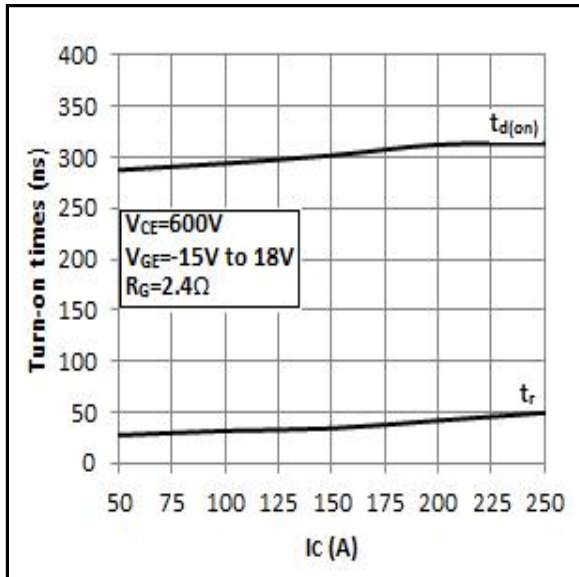


Figure 4: Typical IGBT turn-off switching times vs I_C , $T_j = 25^\circ\text{C}$

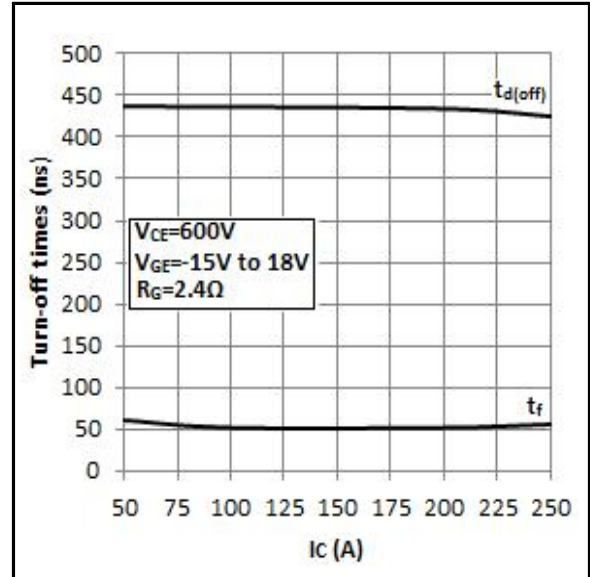


Figure 5: Typical IGBT switching losses vs R_G , $T_j = 25^\circ\text{C}$

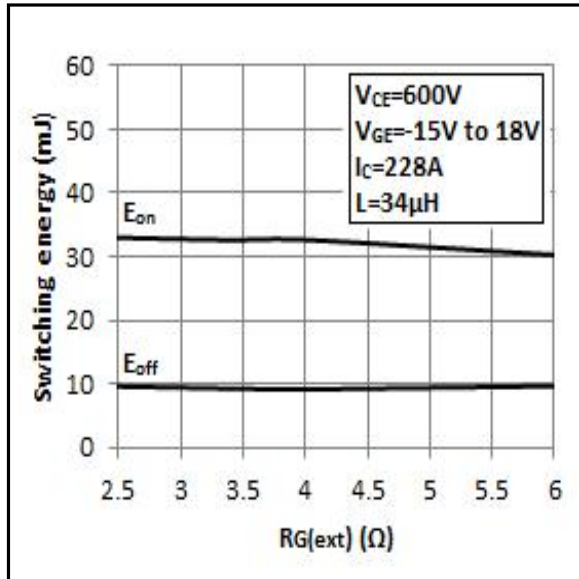
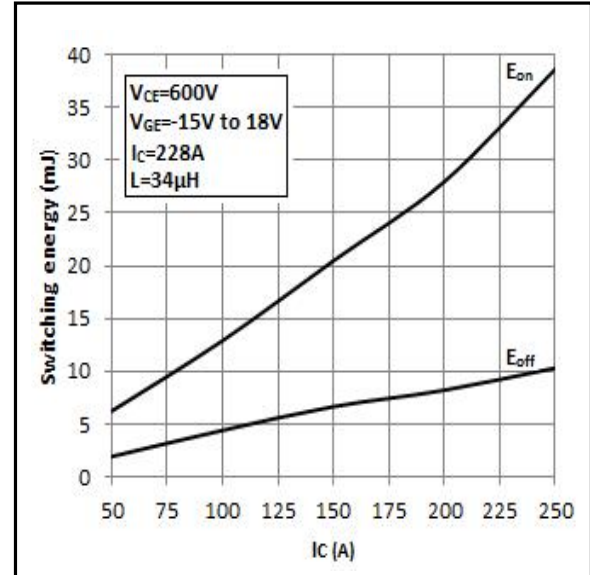
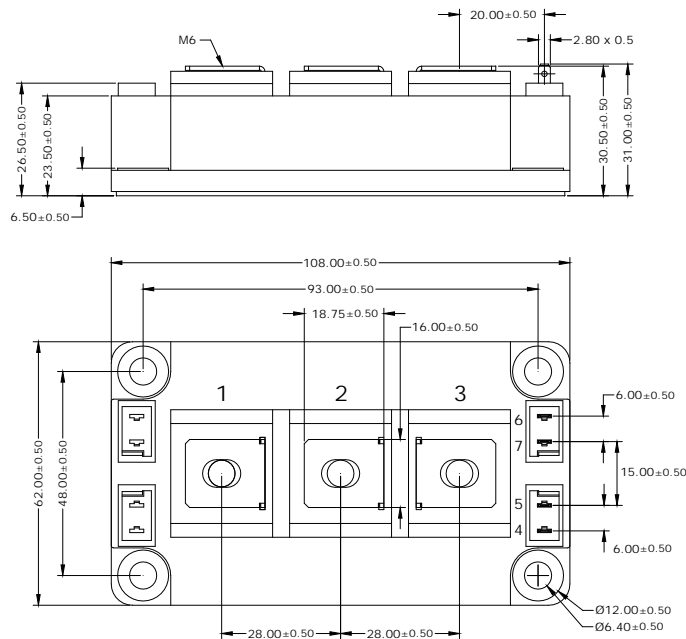


Figure 6: Typical IGBT switching losses vs I_{C} , $T_j = 25^\circ\text{C}$



Package Outline Drawing



CAUTION: These devices are ESD sensitive. Use proper handling procedure.

Disclaimer

These specifications may not be considered as a guarantee of components characteristics. Components have to be tested depending on intended application as adjustments may be necessary. The use of **iQXPRZ Power Inc.** components in life support appliances and systems are subject to written approval of **iQXPRZ Power Inc.**